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Purpose: To provide a technical condensation of information of interest to electronic device failure analysis technicians, engineers, and managers.

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Image showing a clock net on an NVIDIA 28 nm graphics processing unit chip that was illuminated using electron beam absorbed current (EBAC) performed on the backside of the device. The bulk silicon and source/drain diffusions have been removed to enable the nanoprobe to land directly on the silicide source/drain regions. This EBAC/SEM composite image was taken with a DCG Systems nProber with accelerating voltage set to 10 kV. *Photo by Robert H. Newton, DCG Systems, and Jane Li, NVIDIA. First Place Winner in False Color Images, 2013 EDFAS Photo Contest.*

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